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W29N01HV



W29N01HV
1G-BIT 3.3V
NAND FLASH MEMORY



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1. GENERAL DESCRIPTION

The W29N01HV (1G-bit) NAND Flash memory provides a storage solution for embedded systems with limited space, pins and power. It is ideal for code shadowing to RAM, solid state applications and storing media data such as, voice, video, text and photos. The device operates on a single 2.7V to 3.6V power supply with active current consumption as low as 25mA 10uA for CMOS standby current.

The memory array totals 138,412,032 bytes, and organized into 1,024 erasable blocks of 135,168 bytes. Each block consists of 64 programmable pages of 2,112-bytes each. Each page consists of 2,048-bytes for the main data storage area and 64-bytes for the spare data area (The spare area is typically used for error management functions).

The W29N01HV supports the standard NAND flash memory interface using the multiplexed 8-bit bus to transfer data, addresses, and command instructions. The five control signals, CLE, ALE, #CE, #RE and #WE handle the bus interface protocol. Also, the device has two other signal pins, the #WP (Write Protect) and the RY/#BY (Ready/Busy) for monitoring the device status.

2. FEATURES

• Basic Features

- Density : 1Gbit (Single chip solution)
- Vcc : 2.7V to 3.6V
- Bus width : x8
- Operating temperature
 - Industrial: -40°C to 85°C

• Single-Level Cell (SLC) technology.

• Organization

- Density: 1G-bit/128M-byte
- Page size
 - 2,112 bytes (2048 + 64 bytes)
- Block size
 - 64 pages (128K + 4K bytes)

• Highest Performance

- Read performance (Max.)
 - Random read: 25us
 - Sequential read cycle: 25ns
- Write Erase performance
 - Page program time: 250us(typ.)
 - Block erase time: 2ms(typ.)
- Endurance 100,000 Erase/Program Cycles⁽¹⁾
- 10-years data retention

• Command set

- Standard NAND command set
- Additional command support
 - Copy Back

• Lowest power consumption

- Read: 25mA(typ.3V),
- Program/Erase: 25mA(typ.3V),
- CMOS standby: 10uA(typ.)

• Space Efficient Packaging

- 48-pin standard TSOP1
- 48-ball VFBGA
- 63-ball VFBGA
- Contact Winbond for stacked packages/KGD

Note:

1. Endurance specification is based on 1bit/528 byte ECC (Error Correcting Code).



3. PACKAGE TYPES AND PIN CONFIGURATIONS

W29N01HV is offered in a 48-pin TSOP1 package (Code S) and 48-ball VFBGA package (Code D) and 63-ball VFBGA package (Code B) as shown in Figure 3-1 to 3-3, respectively. Package diagrams and dimensions are illustrated in Section: [Package Dimensions](#).

3.1 Pin assignment 48-pin TSOP1(x8)

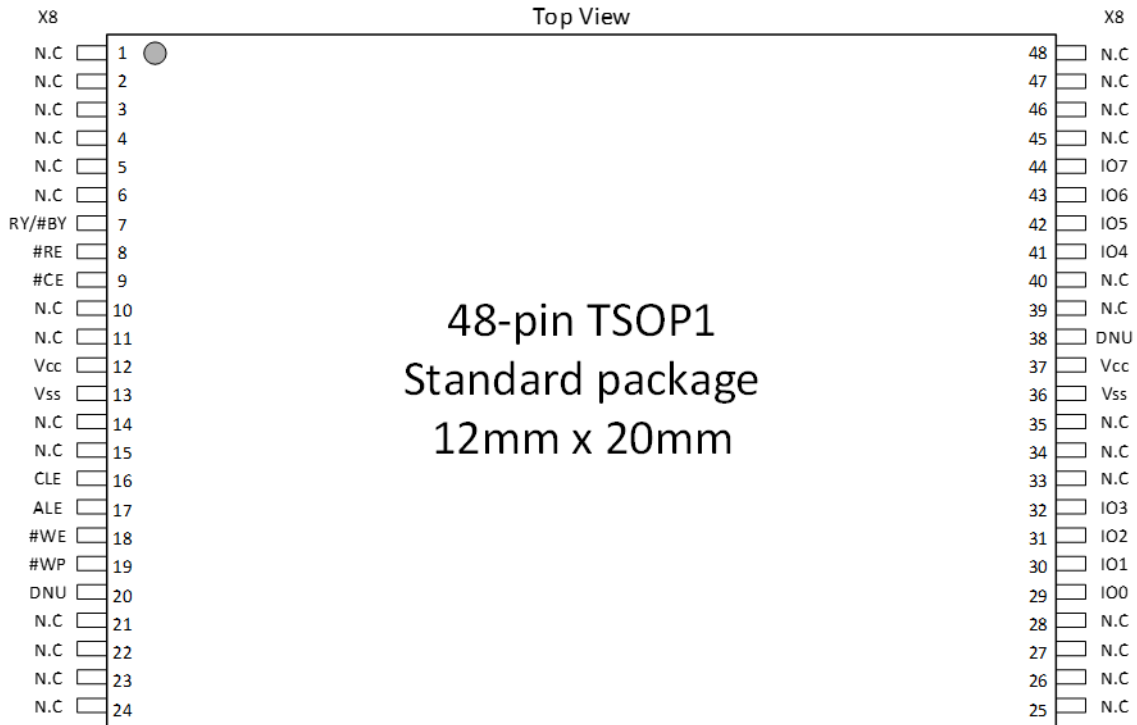


Figure 3-1 Pin Assignment 48-pin TSOP1 (Package code S)



3.2 Pin assignment 48 ball VFBGA (x8)

Top View, ball down

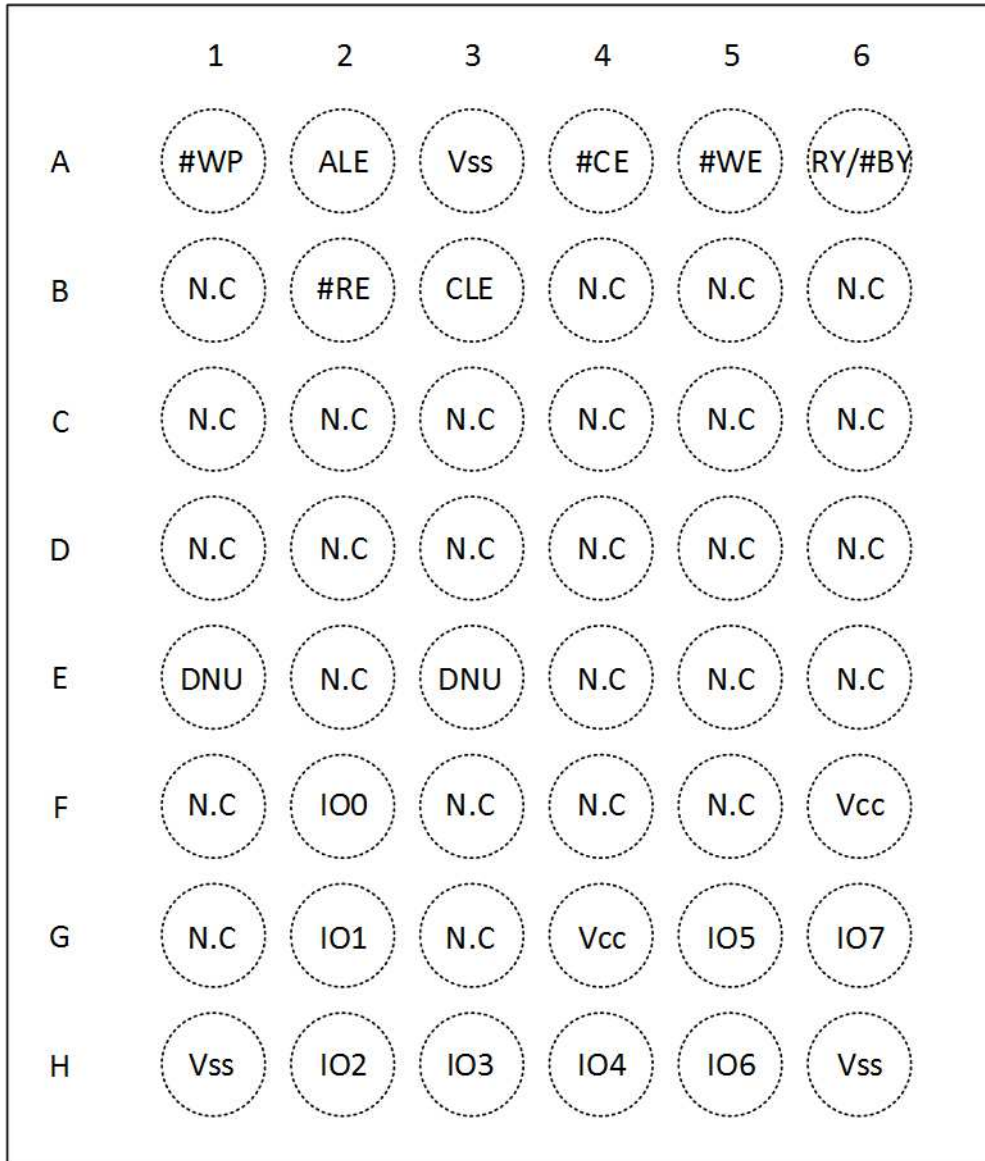


Figure 3-2 Pin Assignment 48-ball VFBGA (Package code D)



3.3 Pin assignment 63 ball VFBGA

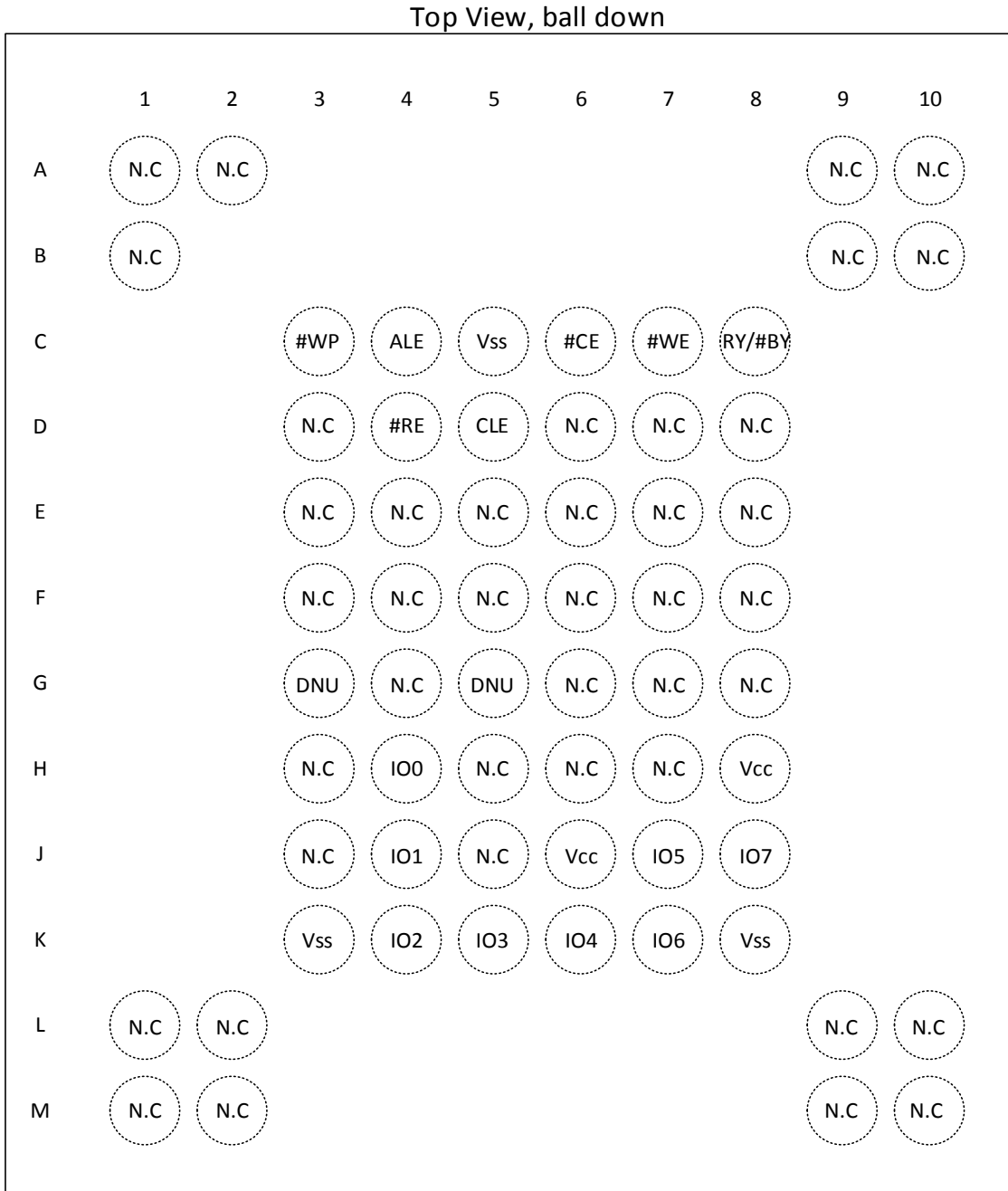


Figure 3-3 Pin Assignment 63-ball VFBGA (Package Code B)



3.4 Pin Descriptions

PIN NAME	I/O	FUNCTION
#WP	I	Write Protect
ALE	I	Address Latch Enable
#CE	I	Chip Enable
#WE	I	Write Enable
RY/#BY	O	Ready/Busy
#RE	I	Read Enable
CLE	I	Command Latch Enable
I/O[0-7]	I/O	Data Input/Output
Vcc	Supply	Power supply
Vss	Supply	Ground
DNU	-	Do Not Use: DNU's must be left unconnected.
N.C	-	No Connect

Table 3.1 Pin Descriptions

Note:

1. Connect all Vcc and Vss pins to power supply or ground. Do not leave Vcc or Vss disconnected.



4. PIN DESCRIPTIONS

4.1 Chip Enable (#CE)

#CE pin enables and disables device operation. When #CE is high the device is disabled and the I/O pins are set to high impedance and enters into standby mode if not busy. When #CE is set low the device will be enabled, power consumption will increase to active levels and the device is ready for Read and Write operations.

4.2 Write Enable (#WE)

#WE pin enables the device to control write operations to input pins of the device. Such as, command instructions, addresses and data that are latched on the rising edge of #WE.

4.3 Read Enable (#RE)

#RE pin controls serial data output from the pre-loaded Data Register. Valid data is present on the I/O bus after the tREA period from the falling edge of #RE. Column addresses are incremented for each #RE pulse.

4.4 Address Latch Enable (ALE)

ALE pin controls address input to the address register of the device. When ALE is active high, addresses are latched via the I/O pins on the rising edge of #WE.

4.5 Command Latch Enable (CLE)

CLE pin controls command input to the command register of the device. When CLE is active high, commands are latched into the command register via I/O pins on the rising edge of #WE.

4.6 Write Protect (#WP)

#WP pin can be used to prevent the inadvertent program/erase to the device. When #WP pin is active low, all program/erase operations are disabled.

4.7 Ready/Busy (RY/#BY)

RY/#BY pin indicates the device status. When RY/#BY output is low, it indicates that the device is processing either a program, erase or read operations. When it returns to high, those operations have completed. RY/#BY pin is an open drain.

4.8 Input and Output (I/Ox)

I/Ox bi-directional pins are used for the following; command, address and data operations.



5. BLOCK DIAGRAM

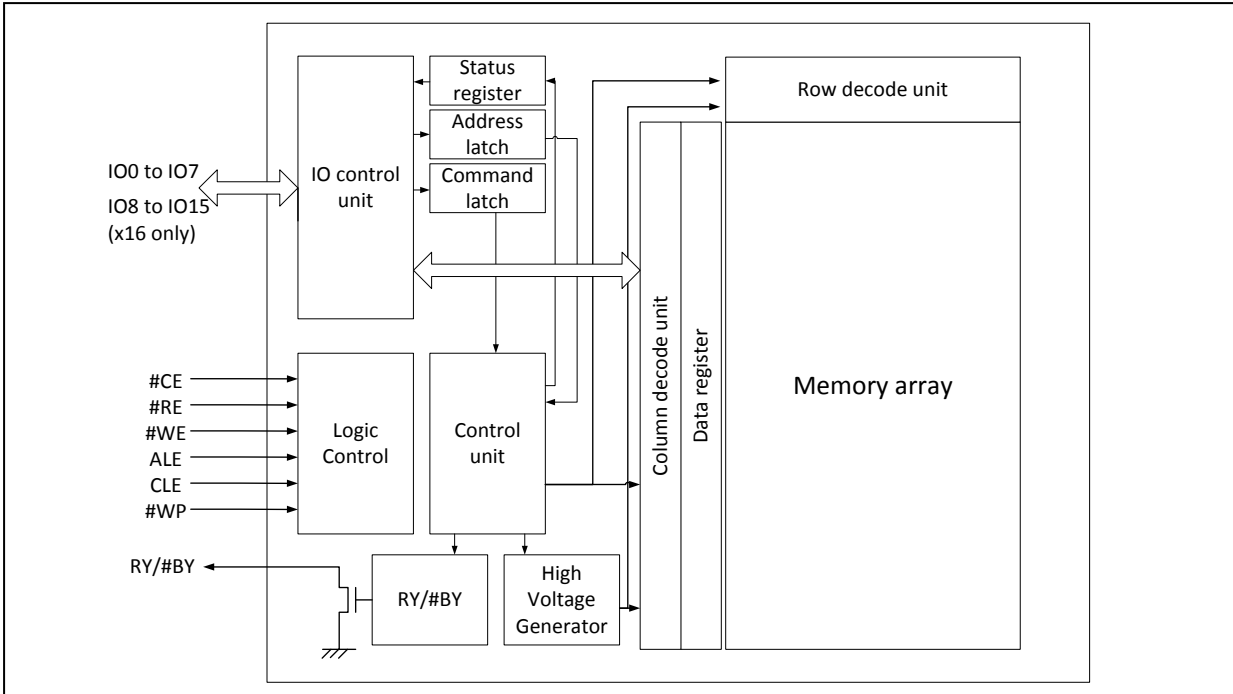


Figure 5-1 NAND Flash Memory Block Diagram



6. MEMORY ARRAY ORGANIZATION

6.1 Array Organization (x8)

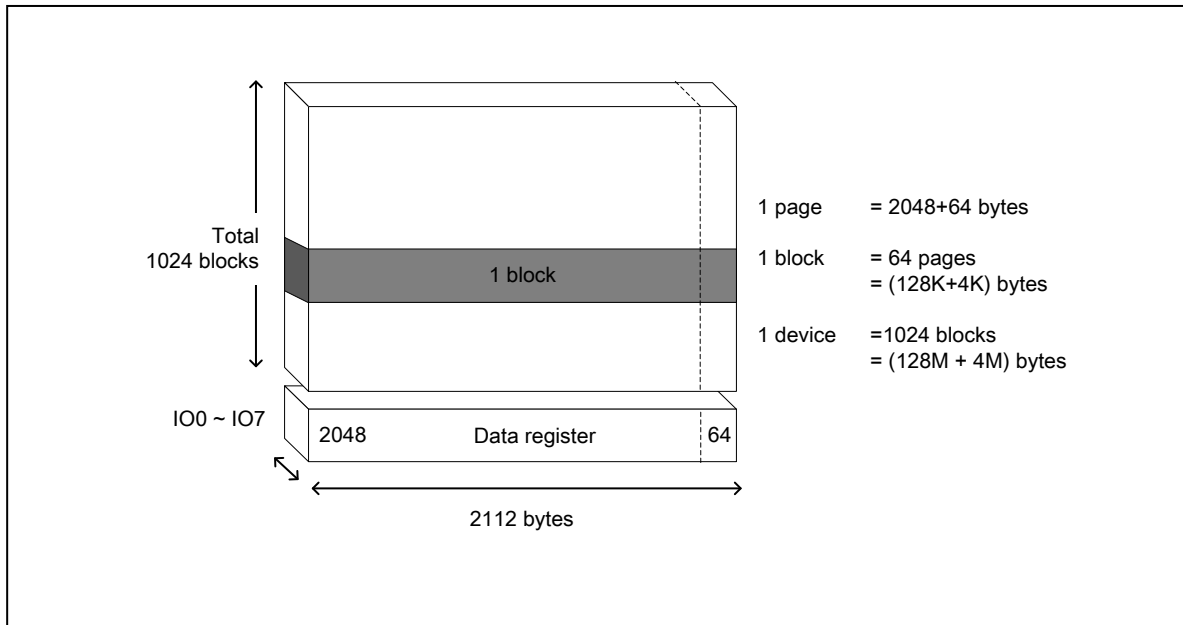


Figure 6-1 Array Organization

	I/O7	I/O6	I/O5	I/O4	I/O3	I/O2	I/O1	I/O0
1 st cycle	A7	A6	A5	A4	A3	A2	A1	A0
2 nd cycle	L	L	L	L	A11	A10	A9	A8
3 rd cycle	A19	A18	A17	A16	A15	A14	A13	A12
4 th cycle	A27	A26	A25	A24	A23	A22	A21	A20

Table 6.1 Addressing

Notes:

1. "L" indicates a low condition, which must be held during the address cycle to insure correct processing.
2. A0 to A11 during the 1st and 2nd cycles are column addresses. A12 to A27 during the 3rd and 4th cycles are row addresses.
3. The device ignores any additional address inputs that exceed the device's requirement.



7. MODE SELECTION TABLE

MODE		CLE	ALE	#CE	#WE	#RE	#WP
Read mode	Command input	H	L	L		H	X
	Address input	L	H	L		H	X
Program Erase mode	Command input	H	L	L		H	H
	Address input	L	H	L		H	H
Data input		L	L	L		H	H
Sequential Read and Data output		L	L	L	H		X
During read (busy)		X	X	X	X	H	X
During program (busy)		X	X	X	X	X	H
During erase (busy)		X	X	X	X	X	H
Write protect		X	X	X	X	X	L
Standby		X	X	H	X	X	0V/Vcc

Table 7.1 Mode Selection

Notes:

1. "H" indicates a HIGH input level, "L" indicates a LOW input level, and "X" indicates a Don't Care Level.
2. #WP should be biased to CMOS HIGH or LOW for standby.



8. COMMAND TABLE

COMMAND	1 ST CYCLE	2 ND CYCLE	3 rd CYCLE	4 th CYCLE	Acceptable during busy
PAGE READ	00h	30h			
READ for COPY BACK	00h	35h			
READ ID	90h				
READ STATUS	70h				Yes
RESET	FFh				Yes
PAGE PROGRAM	80h	10h			
PROGRAM for COPY BACK	85h	10h			
BLOCK ERASE	60h	D0h			
RANDOM DATA INPUT*1	85h				
RANDOM DATA OUTPUT*1	05h	E0h			
READ PARAMETER PAGE	ECh				

Table 8.1 Command Table

Notes:

1. RANDOM DATA INPUT and RANDOM DATA OUTPUT command is only to be used within a page.
2. Any command that are not in the above table are considered as undefined and are prohibited as inputs.



9. DEVICE OPERATIONS

9.1 READ operation

9.1.1 PAGE READ (00h-30h)

When the device powers on, 00h command is latched to command register. Therefore, system only issues four address cycles and 30h command for initial read from the device. This operation can also be entered by writing 00h command to the command register, and then write four address cycles, followed by writing 30h command. After writing 30h command, the data is transferred from NAND array to Data Register during t_R . Data transfer progress can be done by monitoring the status of the RY/#BY signal output. RY/#BY signal will be LOW during data transfer. Also, there is an alternate method by using the READ STATUS (70h) command. If the READ STATUS command is issued during read operation, the Read (00h) command must be re-issued to read out the data from Data Register. When the data transfer is complete, RY/#BY signal goes HIGH, and the data can be read from Data Register by toggling #RE. Read is sequential from initial column address to the end of the page. (See Figure 9-1)

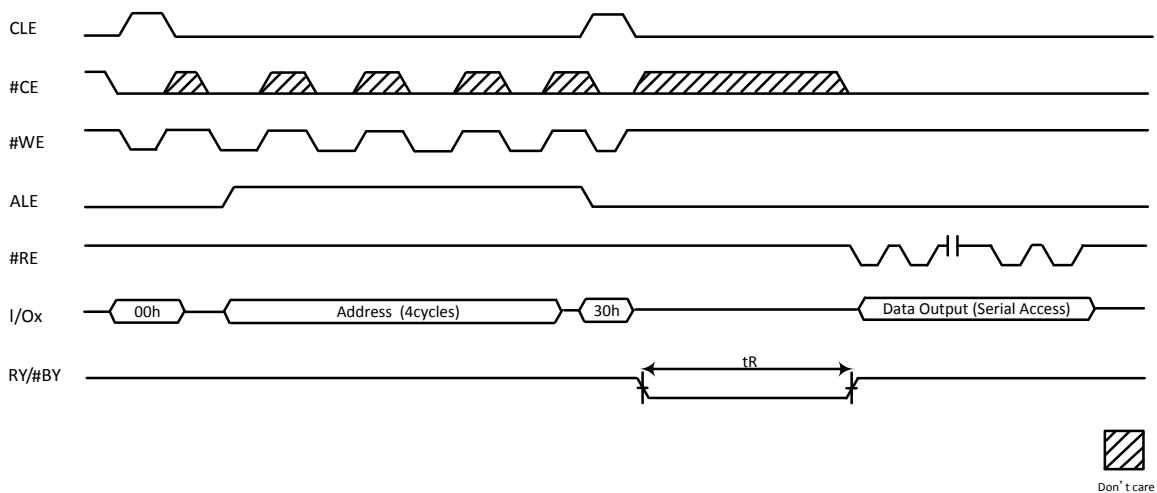


Figure 9-1 Page Read Operations



9.1.2 RANDOM DATA OUTPUT (05h-E0h)

The RANDOM DATA OUTPUT allows the selection of random column addresses to read out data from a single or multiple of addresses. The use of the RANDOM DATA OUTPUT command is available after the PAGE READ (00h-30h) sequence by writing the 05h command following by the two cycle column address and then the E0h command. Toggling #RE will output data sequentially. The RANDOM DATA OUTPUT command can be issued multiple times, but limited to the current loaded page.

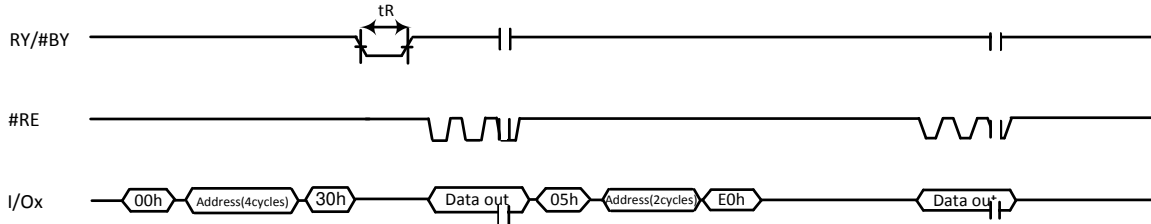


Figure 9-2 Random Data Output

9.1.3 READ ID (90h)

READ ID command is comprised of two modes determined by the input address, device (00h) or ONFI (20h) identification information. To enter the READ ID mode, write 90h to the Command Register followed by a 00h address cycle, then toggle #RE for 5 single byte cycles, W29N01HV. The pre-programmed code includes the Manufacturer ID, Device ID, and Product-Specific Information (see Table 9.1). If the READ ID command is followed by 20h address, the output code includes 4 single byte cycles of ONFI identifying information (See Table 9.2). The device remains in the READ ID Mode until the next valid command is issued.

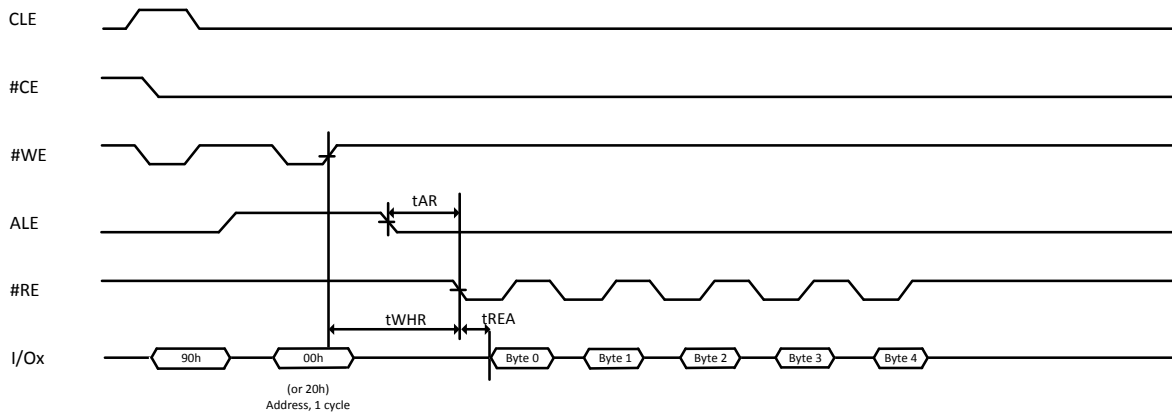


Figure 9-3 Read ID



# of Byte/Cycles	1 st Byte/Cycle	2 nd Byte/Cycle	3 rd Byte/Cycle	4 th Byte/Cycle	5 th Byte/Cycle
W29N01HV	EFh	F1h	00h	95h	00h
Description	MFR ID	Device ID	Cache Programming Non-supported	Page Size:2KB Spare Area Size:64B BLK Size w/o Spare:128KB Organized:x8 or x16 Serial Access:25ns	

Table 9.1 Device ID and configuration codes for Address 00h

# of Byte/Cycles	1 st Byte/Cycle	2 nd Byte/Cycle	3 rd Byte/Cycle	4 th Byte/Cycle
Code	4Fh	4Eh	46h	49h

Table 9.2 ONFI identifying codes for Address 20h

9.1.4 READ PARAMETER PAGE (ECh)

READ PARAMETER PAGE can read out the device’s parameter data structure, such as, manufacturer information, device organization, timing parameters, key features, and other pertinent device parameters. The data structure is stored with at least three copies in the device’s parameter page. Figure 9-4 shows the READ PARAMETER PAGE timing. The RANDOM DATA OUTPUT (05h-E0h) command is supported during data output.

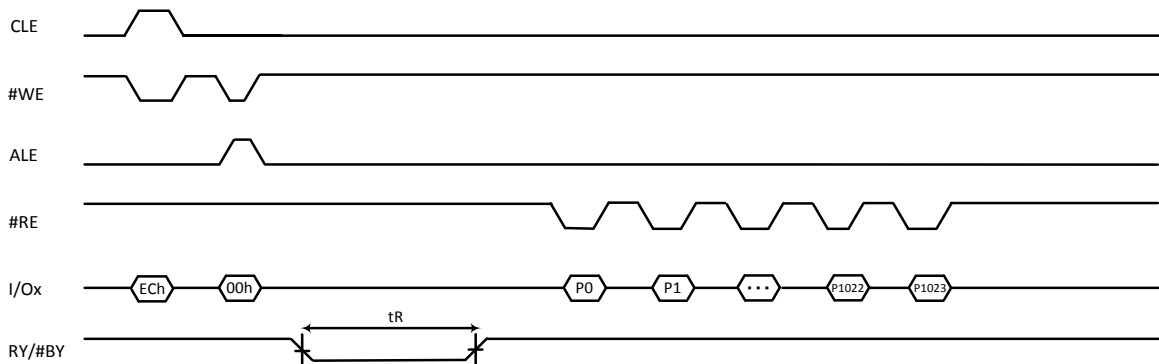


Figure 9-4 Read Parameter Page



9.1.5 READ STATUS (70h)

The W29N01HV has an 8-bit Status Register which can be read during device operation. Refer to Table 9.4 for specific Status Register definitions. After writing 70h command to the Command Register, read cycles will only read from the Status Register. The status can be read from I/O[7:0] outputs, as long as #CE and #RE are LOW. Note; #RE does not need to be toggled for Status Register read. The Command Register remains in status read mode until another command is issued. To change to normal read mode, issue the PAGE READ (00h) command. After the PAGE READ command is issued, data output starts from the initial column address.

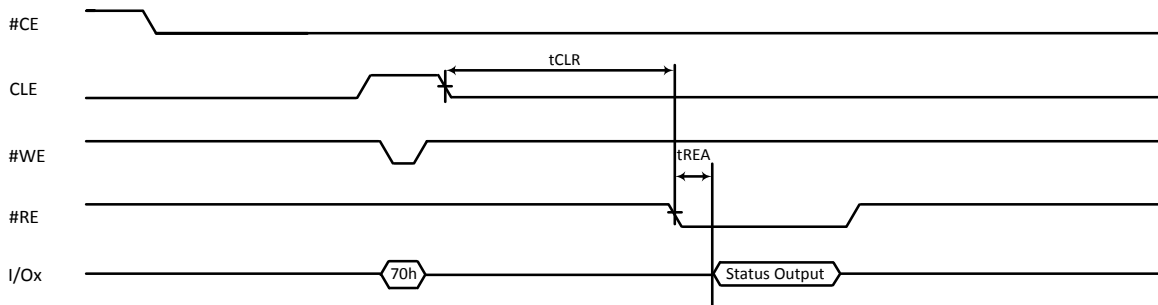


Figure 9-5 Read Status Operation

SR bit	Page Read	Page Program	Block Erase	Definition
I/O 0	Not Use	Pass/Fail	Pass/Fail	0=Successful Program/Erase 1=Error in Program/Erase
I/O 1	Not Use	Not Use	Not Use	0=Successful Program 1=Error in Program
I/O 2	Not Use	Not Use	Not Use	0
I/O 3	Not Use	Not Use	Not Use	0
I/O 4	Not Use	Not Use	Not Use	0
I/O 5	Ready/Busy	Ready/Busy	Ready/Busy	Ready = 1 Busy = 0
I/O 6	Ready/Busy	Ready/Busy	Ready/Busy	Ready = 1 Busy = 0
I/O 7	Write Protect	Write Protect	Write Protect	Unprotected = 1 Protected = 0

Table 9.4 Status Register Bit Definition



9.2 PROGRAM operation

9.2.1 PAGE PROGRAM (80h-10h)

The W29N01HV Page Program command will program pages sequentially within a block, from the lower order page address to higher order page address. Programming pages out of sequence is prohibited. The W29N01HV supports partial-page programming operations up to 4 times before an erase is required if partitioning a page. Note; programming a single bit more than once without first erasing it is not supported.

9.2.2 SERIAL DATA INPUT (80h)

Page Program operation starts with the execution of the Serial Data Input command (80h) to the Command Register, following next by inputting four address cycles and then the data is loaded. Serial data is loaded to Data register with each #WE cycle. The Program command (10h) is written to the Command Register after the serial data input is finished. At this time the internal write state controller automatically executes the algorithms for program and verifies operations. Once the programming starts, determining the completion of the program process can be done by monitoring the RY/#BY output or the Status Register Bit 6, which will follow the RY/#BY signal. RY/#BY will stay LOW during the internal array programming operation during the period of (tPROG). During page program operation, only two commands are available, READ STATUS (70h) and RESET (FFh). When the device status goes to the ready state, Status Register Bit 0 (I/O0) indicates whether the program operation passed (Bit0=0) or failed (Bit0=1), (see Figure 9-6). The Command Register remains in read status mode until the next command is issued.

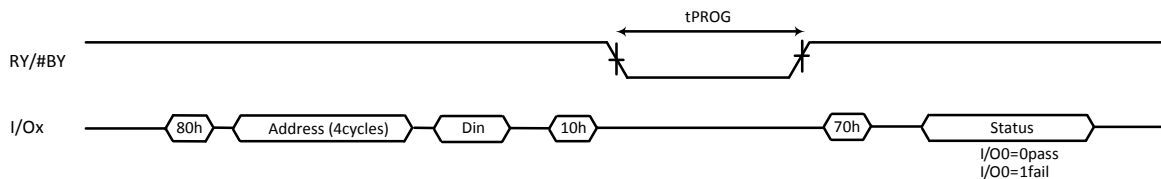


Figure 9-6 Page Program



9.2.3 RANDOM DATA INPUT (85h)

After the Page Program (80h) execution of the initial data has been loaded into the Data register, if the need for additional writing of data is required, using the RANDOM DATA INPUT (85h) command can perform this function to a new column address prior to the Program (10h) command. The RANDOM DATA INPUT command can be issued multiple times in the same page (See Figure 9-7).

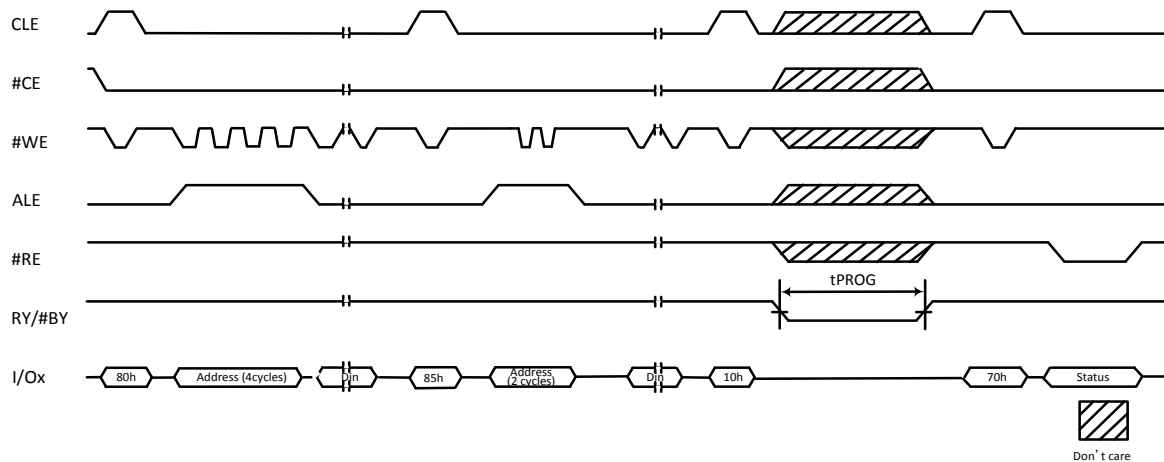


Figure 9-7 Random Data Input



9.3 COPY BACK operation

Copy Back operations require two command sets. Issue a READ for COPY BACK (00h-35h) command first, then the PROGRAM for COPY BACK (85h-10h) command.

9.3.1 READ for COPY BACK (00h-35h)

The READ for COPY BACK command is used together with the PROGRAM for COPY BACK (85h-10h) command. To start execution, READ for COPY BACK (00h) command is written to the Command Register, followed by the four cycles of the source page address. To start the transfer of the selected page data from the memory array to the Data register, write the 35h command to the Command Register.

After execution of the READ for COPY BACK command sequence and RY/#BY returns to HIGH marking the completion of the operation, the transferred data from the source page into the Data register may be read out by toggling #RE. Data is output sequentially from the column address that was originally specified with the READ for COPY BACK command. RANDOM DATA OUTPUT (05h-E0h) commands can be issued multiple times without any limitation after READ for COPY BACK command has been executed (see Figures 9-8 and 9-9).

At this point the device is in ready state to accept the PROGRAM for COPY BACK command.

9.3.2 PROGRAM for COPY BACK (85h-10h)

After the READ for COPY BACK command operation has been completed and RY/#BY goes HIGH, the PROGRAM for COPY BACK command can be written to the Command Register. The command results in the transfer of data to the Data Register, then internal operations start programming of the new destination page. The sequence would be, write 85h to the Command Register, followed by the four cycle destination page address to the NAND array. Next write the 10h command to the Command Register; this will signal the internal controller to automatically start to program the data to new destination page. During this programming time, RY/#BY will LOW. The READ STATUS command can be used instead of the RY/#BY signal to determine when the program is complete. When Status Register Bit 6 (I/O6) equals to "1", Status Register Bit 0 (I/O0) will indicate if the operation was successful or not.

The RANDOM DATA INPUT (85h) command can be used during the PROGRAM for COPY BACK command for modifying the original data. Once the data is copied into the Data register using the READ for COPY BACK (00h-35h) command, follow by writing the RANDOM DATA INPUT (85h) command, along with the address of the data to be changed. The data to be changed is placed on the external data pins. This operation copies the data into the Data register. Once the 10h command is written to the Command Register, the original data and the modified data are transferred to the Data Register, and programming of the new page commences. The RANDOM DATA INPUT command can be issued numerous times without limitation, as necessary before starting the programming sequence with 10h command.

Since COPY BACK operations do not use external memory and the data of source page might include a bit errors, a competent ECC scheme should be developed to check the data before programming data to a new destination page.

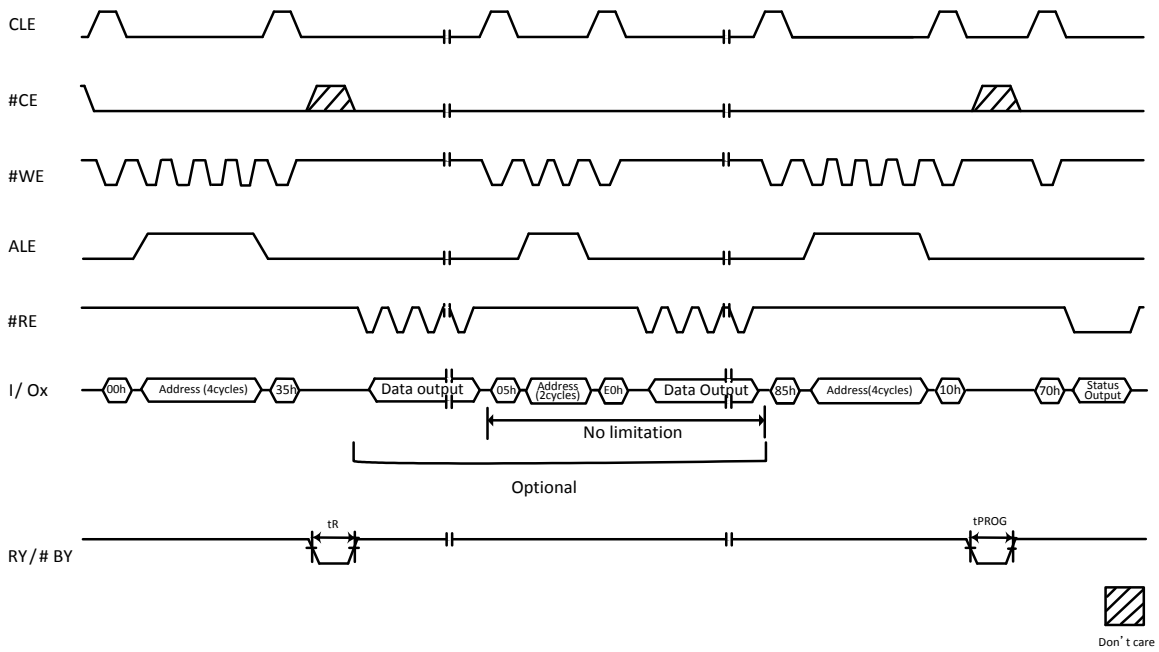


Figure 9-8 Copy Back Program Operation

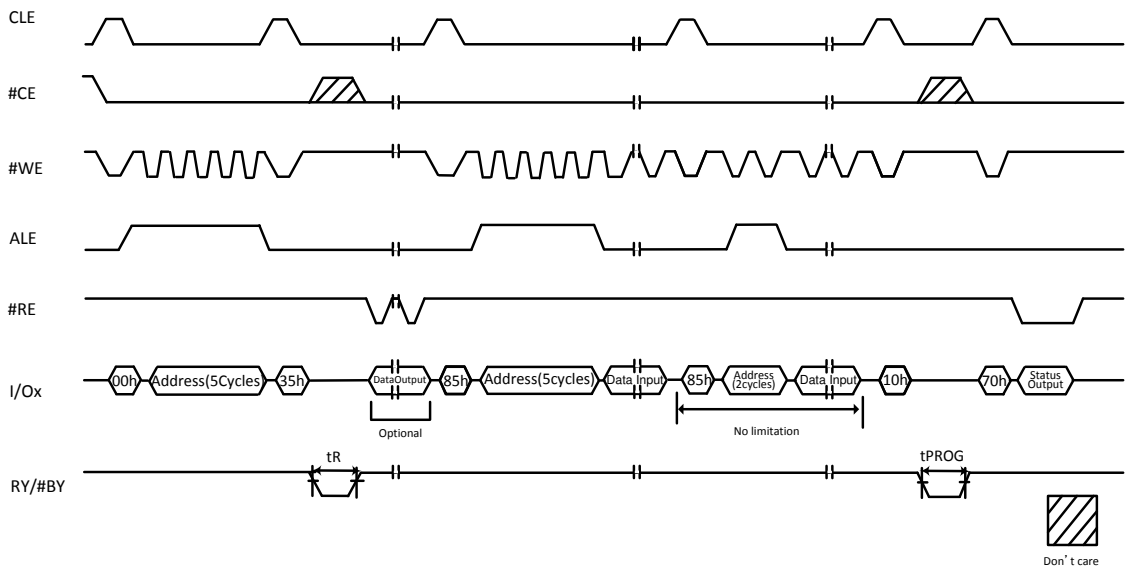


Figure 9-9 Copy Back Operation with Random Data Input